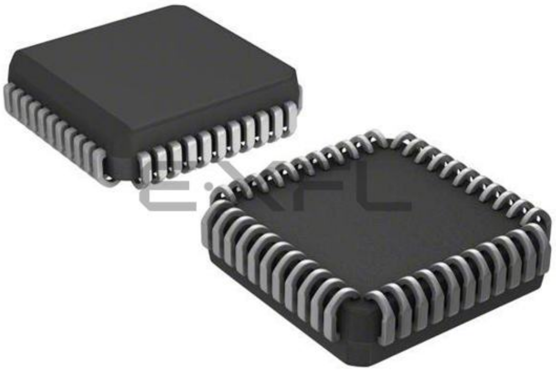


Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18c442-e-l

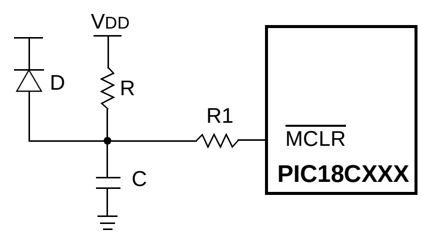
NOTES:

3.1 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when V_{DD} rise is detected. To take advantage of the POR circuitry, just tie the $\overline{\text{MCLR}}$ pin directly (or through a resistor) to V_{DD}. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for V_{DD} is specified (parameter D004). For a slow rise time, see Figure 3-2.

When the device starts normal operation (i.e., exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

FIGURE 3-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW V_{DD} POWER-UP)



Note 1: External Power-on Reset circuit is required only if the V_{DD} power-up slope is too slow. The diode D helps discharge the capacitor quickly when V_{DD} powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$/V_{PP} pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

3.2 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter #33) only on power-up from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows V_{DD} to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip-to-chip due to V_{DD}, temperature and process variation. See DC parameter #33 for details.

3.3 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter #32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

3.4 PLL Lock Time-out

With the PLL enabled, the time-out sequence following a Power-on Reset is different from other oscillator modes. A portion of the Power-up Timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (T_{PLL}) is typically 2 ms and follows the oscillator start-up time-out (OST).

3.5 Brown-out Reset (BOR)

A configuration bit, BOREN, can disable (if clear/programmed), or enable (if set) the Brown-out Reset circuitry. If V_{DD} falls below parameter D005 for greater than parameter #35, the brown-out situation will reset the chip. A RESET may not occur if V_{DD} falls below parameter D005 for less than parameter #35. The chip will remain in Brown-out Reset until V_{DD} rises above BV_{DD}. The Power-up Timer will then be invoked and will keep the chip in RESET an additional time delay (parameter #33). If V_{DD} drops below BV_{DD} while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once V_{DD} rises above BV_{DD}, the Power-up Timer will execute the additional time delay.

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: First, PWRT time-out is invoked after the POR time delay has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 3-3, Figure 3-4, Figure 3-5, Figure 3-6 and Figure 3-7 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Bringing $\overline{\text{MCLR}}$ high will begin execution immediately (Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC18CXXX device operating in parallel.

Table 3-2 shows the RESET conditions for some Special Function Registers, while Table 3-3 shows the RESET conditions for all the registers.

FIGURE 4-6: DATA MEMORY MAP FOR PIC18C242/442

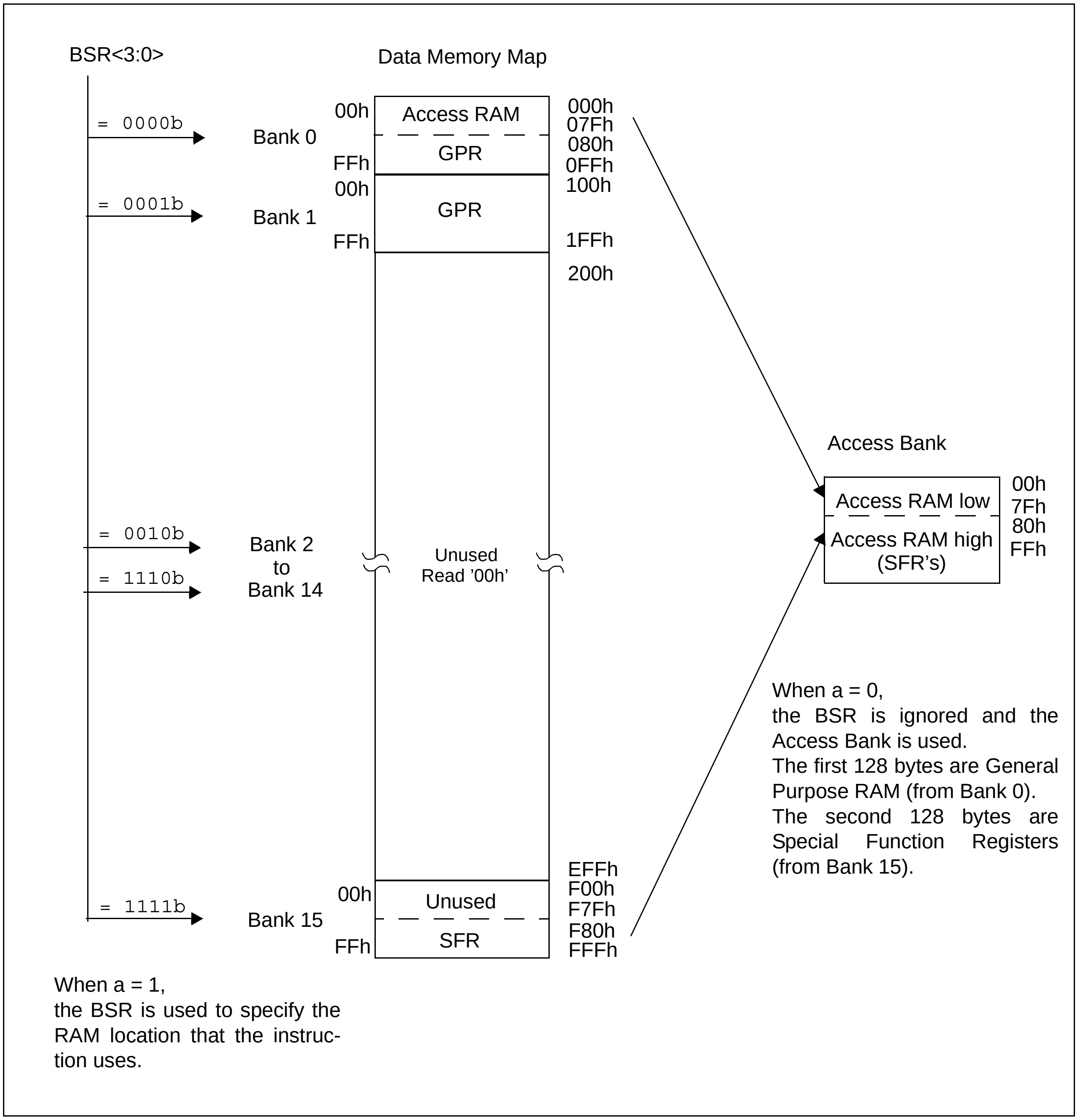


TABLE 4-2: REGISTER FILE SUMMARY (CONTINUED)

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Details on page:
IPR2	—	—	—	—	BCLIP	LVDIP	TMR3IP	CCP2IP	---- 1111	73
PIR2	—	—	—	—	BCLIF	LVDIF	TMR3IF	CCP2IF	---- 0000	69
PIE2	—	—	—	—	BCLIE	LVDIE	TMR3IE	CCP2IE	---- 0000	71
IPR1	PSPIP	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111 1111	72
PIR1	PSPIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	68
PIE1	PSPIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	70
TRISE	IBF	OBF	IBOV	PSPMODE	—	Data Direction bits for PORTE			0000 -111	88
TRISD	Data Direction Control Register for PORTD								1111 1111	85
TRISC	Data Direction Control Register for PORTC								1111 1111	83
TRISB	Data Direction Control Register for PORTB								1111 1111	80
TRISA	—	TRISA6(1)	Data Direction Control Register for PORTA						-111 1111	77
LATE	—	—	—	—	—	Read PORTE Data Latch, Write PORTE Data Latch			---- -xxx	87
LATD	Read PORTD Data Latch, Write PORTD Data Latch								xxxx xxxx	85
LATC	Read PORTC Data Latch, Write PORTC Data Latch								xxxx xxxx	83
LATB	Read PORTB Data Latch, Write PORTB Data Latch								xxxx xxxx	80
LATA	—	LATA6(1)	Read PORTA Data Latch, Write PORTA Data Latch(1)						-xxx xxxx	77
PORTE	Read PORTE pins, Write PORTE Data Latch								---- -000	87
PORTD	Read PORTD pins, Write PORTD Data Latch								xxxx xxxx	85
PORTC	Read PORTC pins, Write PORTC Data Latch								xxxx xxxx	83
PORTB	Read PORTB pins, Write PORTB Data Latch								xxxx xxxx	80
PORTA	—	RA6(1)	Read PORTA pins, Write PORTA Data Latch(1)						-x0x 0000	77

Legend: x = unknown, u = unchanged, - = unimplemented, q = value depends on condition

Note 1: RA6 and associated bits are configured as port pins in RCIO and ECIO oscillator mode only, and read '0' in all other oscillator modes.

2: Bit 21 of the TBLPTRU allows access to the device configuration bits.

4.13 STATUS Register

The STATUS register, shown in Register 4-2, contains the arithmetic status of the ALU. The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC, C, OV or N bits, then the write to these five bits is disabled. These bits are set or cleared according to the device logic. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF`, `MOVFF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, DC, OV or N bits from the STATUS register. For other instructions not affecting any status bits, see Table 19-2.

Note:	The C and DC bits operate as a $\overline{\text{borrow}}$ and $\overline{\text{digit borrow}}$ bit respectively, in subtraction.

REGISTER 4-2: STATUS REGISTER

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	N	OV	Z	DC	C
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **N:** Negative bit
This bit is used for signed arithmetic (2's complement). It indicates whether the result was negative, (ALU MSB = 1).
`1` = Result was negative
`0` = Result was positive

bit 3 **OV:** Overflow bit
This bit is used for signed arithmetic (2's complement). It indicates an overflow of the 7-bit magnitude, which causes the sign bit (bit7) to change state.
`1` = Overflow occurred for signed arithmetic (in this arithmetic operation)
`0` = No overflow occurred

bit 2 **Z:** Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit carry/$\overline{\text{borrow}}$ bit
For `ADDWF`, `ADDLW`, `SUBLW`, and `SUBWF` instructions
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

Note: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the bit 4 or bit 3 of the source register.

bit 0 **C:** Carry/$\overline{\text{borrow}}$ bit
For `ADDWF`, `ADDLW`, `SUBLW`, and `SUBWF` instructions
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

REGISTER 8-1: TRISE REGISTER

R-0	R-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
IBF	OBF	IBOV	PSPMODE	—	TRISE2	TRISE1	TRISE0
bit 7							bit 0

bit 7 **IBF:** Input Buffer Full Status bit
1 = A word has been received and waiting to be read by the CPU
0 = No word has been received

bit 6 **OBF**: Output Buffer Full Status bit
1 = The output buffer still holds a previously written word
0 = The output buffer has been read

bit 5 **IBOV**: Input Buffer Overflow Detect bit (in Microprocessor mode)
1 = A write occurred when a previously input word has not been read (must be cleared in software)
0 = No overflow occurred

bit 4 **PSPMODE**: Parallel Slave Port Mode Select bit
1 = Parallel Slave Port mode
0 = General purpose I/O mode

bit 3 **Unimplemented:** Read as '0'

bit 2 **TRISE2**: RE2 Direction Control bit
1 = Input
0 = Output

bit 1 **TRISE1**: RE1 Direction Control bit
1 = Input
0 = Output

bit 0 **TRISE0**: RE0 Direction Control bit
1 = Input
0 = Output

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

15.4.2 USART SYNCHRONOUS SLAVE RECEPTION

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode and bit SREN, which is a “don't care” in Slave mode.

If receive is enabled by setting bit CREN prior to the `SLEEP` instruction, then a word may be received during SLEEP. On completely receiving the word, the RSR register will transfer the data to the RCREG register, and if enable bit RCIE bit is set, the interrupt generated will wake the chip from SLEEP. If the global interrupt is enabled, the program will branch to the interrupt vector.

To set up a Synchronous Slave Reception:

1. Enable the synchronous master serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. If interrupts are desired, set enable bit RCIE.
3. If 9-bit reception is desired, set bit RX9.
4. To enable reception, set enable bit CREN.
5. Flag bit RCIF will be set when reception is complete. An interrupt will be generated if enable bit RCIE was set.
6. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
7. Read the 8-bit received data by reading the RCREG register.
8. If any error occurred, clear the error by clearing bit CREN.

TABLE 15-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 -00x	0000 -00x
RCREG	USART Receive Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'.
Shaded cells are not used for Synchronous Slave Reception.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18C2X2 devices. Always maintain these bits clear.

16.0 COMPATIBLE 10-BIT ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The analog-to-digital (A/D) converter module has five inputs for the PIC18C2x2 devices and eight for the PIC18C4x2 devices. This module has the ADCON0 and ADCON1 register definitions that are compatible with the mid-range A/D module.

The A/D allows conversion of an analog input signal to a corresponding 10-bit digital number.

The A/D module has four registers. These registers are:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

The ADCON0 register, shown in Register 16-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 16-2, configures the functions of the port pins.

REGISTER 16-1: ADCON0 REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON
bit 7							bit 0

bit 7-6 **ADCS1:ADCS0:** A/D Conversion Clock Select bits (ADCON0 bits in **bold**)

ADCON1 <ADCS2>	ADCON0 <ADCS1:ADCS0>	Clock Conversion
0	**00**	FOSC/2
0	**01**	FOSC/8
0	**10**	FOSC/32
0	**11**	FRC (clock derived from the internal A/D RC oscillator)
1	**00**	FOSC/4
1	**01**	FOSC/16
1	**10**	FOSC/64
1	**11**	FRC (clock derived from the internal A/D RC oscillator)

bit 5-3 **CHS2:CHS0:** Analog Channel Select bits
000 = channel 0 (AN0)
001 = channel 1 (AN1)
010 = channel 2 (AN2)
011 = channel 3 (AN3)
100 = channel 4 (AN4)
101 = channel 5 (AN5)
110 = channel 6 (AN6)
111 = channel 7 (AN7)

Note: The PIC18C2X2 devices do not implement the full 8 A/D channels; the unimplemented selections are reserved. Do not select any unimplemented channel.

bit 2 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
When ADON = 1:
1 = A/D conversion in progress (setting this bit starts the A/D conversion which is automatically cleared by hardware when the A/D conversion is complete)
0 = A/D conversion not in progress

bit 1 **Unimplemented:** Read as '0'

bit 0 **ADON:** A/D On bit
1 = A/D converter module is powered up
0 = A/D converter module is shut-off and consumes no operating current

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR reset	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}) or the voltage level on the RA3/AN3/V_{REF}+ pin and RA2/AN2/V_{REF}-.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in SLEEP, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

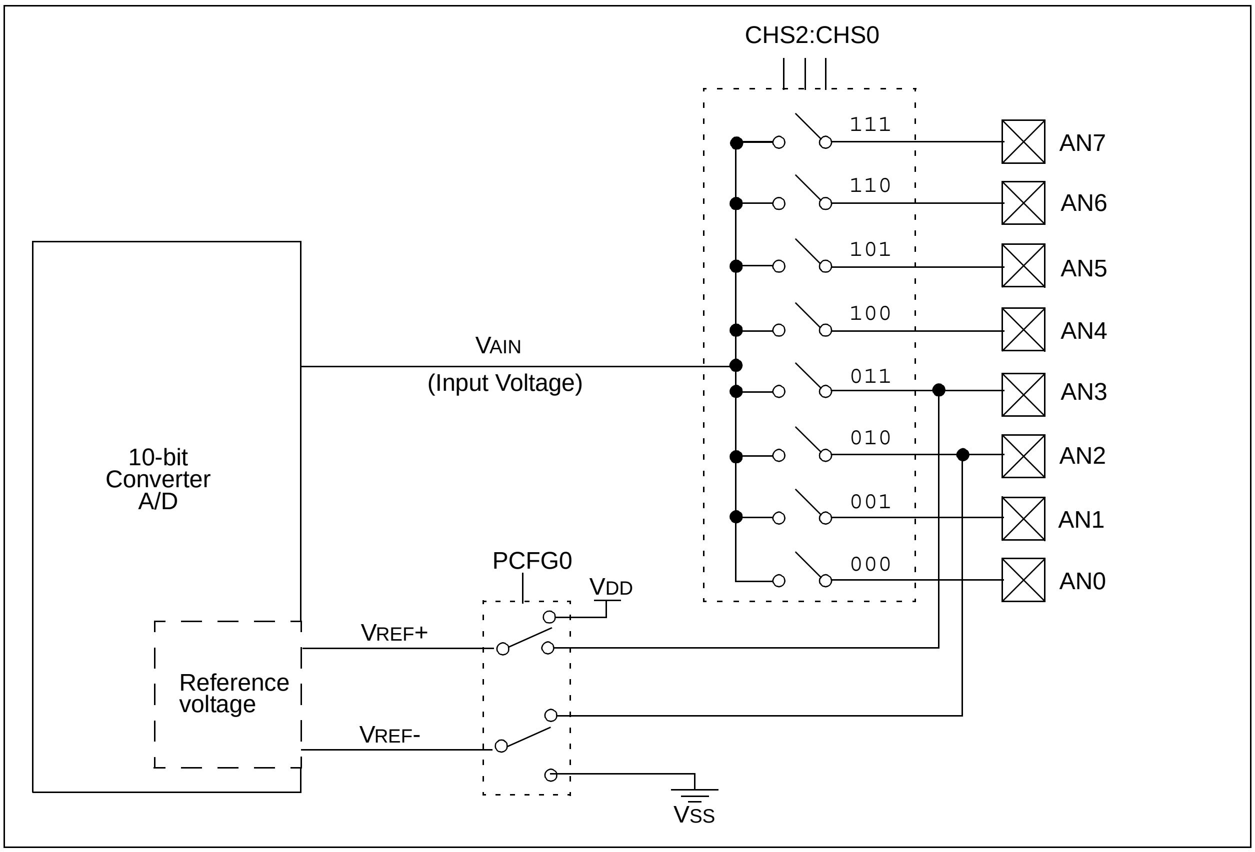
The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device RESET forces all registers to their RESET state. This forces the A/D module to be turned off and any conversion is aborted.

Each port pin associated with the A/D converter can be configured as an analog input (RA3 can also be a voltage reference) or as a digital I/O.

The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH/ADRESL registers, the GO/$\overline{\text{DONE}}$ bit (ADCON0<2>) is cleared, and A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 16-1.

FIGURE 16-1: A/D BLOCK DIAGRAM



MOVFF — Move f to f

Syntax: [*label*] MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	$ffff_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096 byte data space (000h to FFFh), and location of destination 'f_d' can also be anywhere from 000h to FFFh.
Either source or destination can be WREG (a useful special situation).
`MOVFF` is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).

The `MOVFF` instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

Words: 2

Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: `MOVFF   REG1, REG2`

Before Instruction
```
REG1     =   0x33
REG2     =   0x11
```
After Instruction
```
REG1     =   0x33,
REG2     =   0x33
```

MOVLB — Move literal to low nibble in BSR

Syntax: [*label*] MOVLB k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow$ BSR

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The 8-bit literal 'k' is loaded into the Bank Select Register (BSR).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: `MOVLB   5`

Before Instruction
```
BSR register   =   0x02
```
After Instruction
```
BSR register   =   0x05
```

SLEEP — Enter SLEEP mode

Syntax:	[*label*] SLEEP
Operands:	None
Operation:	00h → WDT, 0 → WDT postscaler, 1 → $\overline{TO}$, 0 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Encoding:	`0000 0000 0000 0011`
Description:	The power-down status bit ($\overline{PD}$) is cleared. The time-out status bit ($\overline{TO}$) is set. Watchdog Timer and its postscaler are cleared. The processor is put into SLEEP mode with the oscillator stopped.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	Go to sleep

Example: `SLEEP`

Before Instruction
```
TO  =  ?
PD  =  ?
```
After Instruction
```
TO  =  1 †
PD  =  0
```

† If WDT causes wake-up, this bit is cleared.

SUBFWB — Subtract f from WREG with borrow

Syntax:	[*label*] SUBFWB f [,d [,a]
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$
Operation:	(WREG) – (f) – ($\overline{C}$) → dest
Status Affected:	N,OV, C, DC, Z
Encoding:	`0101 01da ffff ffff`
Description:	Subtract register 'f' and carry flag (borrow) from WREG (2's complement method). If 'd' is 0, the result is stored in WREG. If 'd' is 1, the result is stored in register 'f' (default). If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' is 1, then the bank will be selected as per the BSR value (default).
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: `SUBFWB   REG, 1, 0`

Before Instruction
```
REG    =  3
WREG   =  2
C      =  1
```
After Instruction
```
REG    =  FF
WREG   =  2
C      =  0
Z      =  0
N      =  1     ; result is negative
```

Example 2: `SUBFWB   REG, 0, 0`

Before Instruction
```
REG    =  2
WREG   =  5
C      =  1
```
After Instruction
```
REG    =  2
WREG   =  3
C      =  1
Z      =  0
N      =  0     ; result is positive
```

Example 3: `SUBFWB   REG, 1, 0`

Before Instruction
```
REG    =  1
WREG   =  2
C      =  0
```
After Instruction
```
REG    =  0
WREG   =  2
C      =  1
Z      =  1     ; result is zero
N      =  0
```

20.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD for PIC16F87X
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

20.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

20.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

20.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

20.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC16F87X and can be used to develop for this and other PIC microcontrollers from the PIC16CXXX family. The MPLAB ICD utilizes the in-circuit debugging capability built into the PIC16F87X. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

20.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

20.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

20.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

20.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C™ bus and separate headers for connection to an LCD module and a keypad.

21.1 DC Characteristics

PIC18LCXX2 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18CXX2 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC18LCXX2	2.5	—	5.5	V	HS, XT, RC and LP osc mode
D001		PIC18CXX2	4.2	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage**(1)	1.5	—	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	—	0.7	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See section on Power-on Reset for details
	VBOR	**Brown-out Reset Voltage**					
D005		PIC18LCXX2					
		BORV1:BORV0 = 11	2.5	—	2.66	V	
		BORV1:BORV0 = 10	2.7	—	2.86	V	
		BORV1:BORV0 = 01	4.2	—	4.46	V	
		BORV1:BORV0 = 00	4.5	—	4.78	V	
D005		PIC18CXX2					
		BORV1:BORV0 = 1x	N.A.	—	N.A.	V	Not in operating voltage range of device
		BORV1:BORV0 = 01	4.2	—	4.46	V	
		BORV1:BORV0 = 00	4.5	—	4.78	V	

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

21.1 DC Characteristics (Continued)

PIC18LCXX2 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18CXX2 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial; -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current(2,4)**					
D010		PIC18LCXX2	—	—	2	mA	XT, RC, RCIO osc configurations FOSC = 4 MHz, VDD = 2.5V
D010		PIC18CXX2	—	—	4	mA	XT, RC, RCIO osc configurations FOSC = 4 MHz, VDD = 4.2V
D010A		PIC18LCXX2	—	—	55	μA	LP osc configuration FOSC = 32 kHz, VDD = 2.5V
D010A		PIC18CXX2	—	—	250	μA	LP osc configuration FOSC = 32 kHz, VDD = 4.2V
D010C		PIC18LCXX2	—	—	38	mA	EC, ECIO osc configurations FOSC = 40 MHz, VDD = 5.5V
D010C		PIC18CXX2	—	—	38	mA	EC, ECIO osc configurations FOSC = 40 MHz, VDD = 5.5V
D013		PIC18LCXX2	 — — —	 — — —	 3.5 25 38	 mA mA mA	HS osc configuration FOSC = 6 MHz, VDD = 2.5V FOSC = 25 MHz, VDD = 5.5V HS + PLL osc configurations FOSC = 10 MHz, VDD = 5.5V
D013		PIC18CXX2	 — —	 — —	 25 38	 mA mA	HS osc configuration FOSC = 25 MHz, VDD = 5.5V HS + PLL osc configurations FOSC = 10 MHz, VDD = 5.5V
D014		PIC18LCXX2	 —	 —	 55	 μA	Timer1 osc configuration FOSC = 32 kHz, VDD = 2.5V
D014		PIC18CXX2	 — —	 — —	 200 250	 μA μA	OSCB osc configuration FOSC = 32 kHz, VDD = 4.2V, -40°C to +85°C FOSC = 32 kHz, VDD = 4.2V, -40°C to +125°C

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
$\overline{\text{OSC1}}$ = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

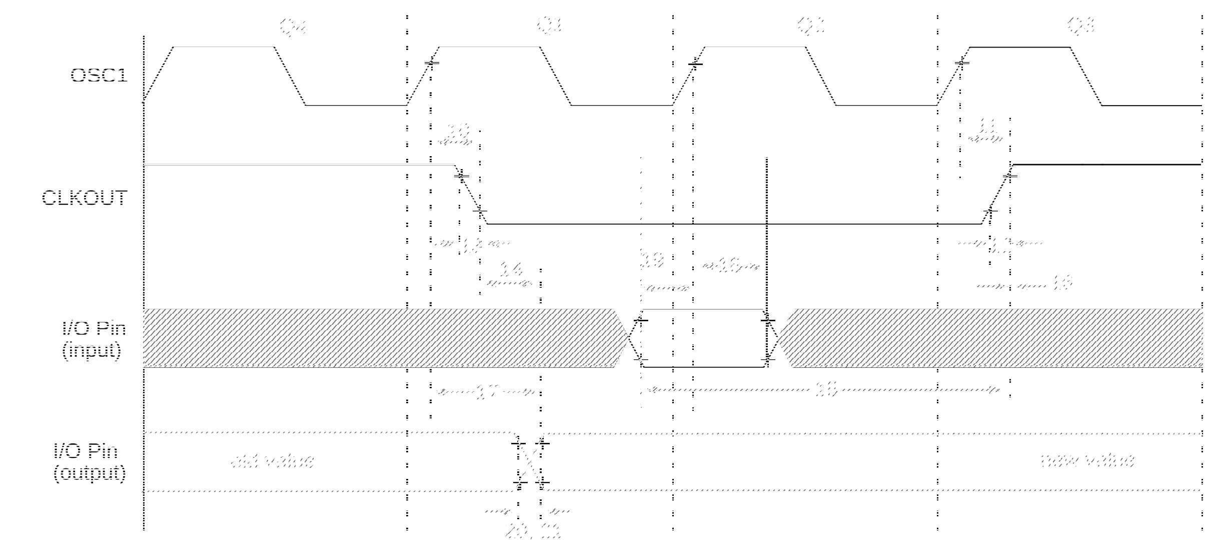
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

TABLE 21-5: PLL CLOCK TIMING SPECIFICATION (VDD = 4.2V - 5.5V)

Param No.	Symbol	Characteristic	Min	Max	Units	Conditions
	TRC	PLL Start-up Time (Lock Time)	—	2	ms	
	ΔCLK	CLKOUT Stability (Jitter) using PLL	-2	+2	%	

FIGURE 21-6: CLKOUT AND I/O TIMING



Note: Refer to Figure 21-4 for load conditions.

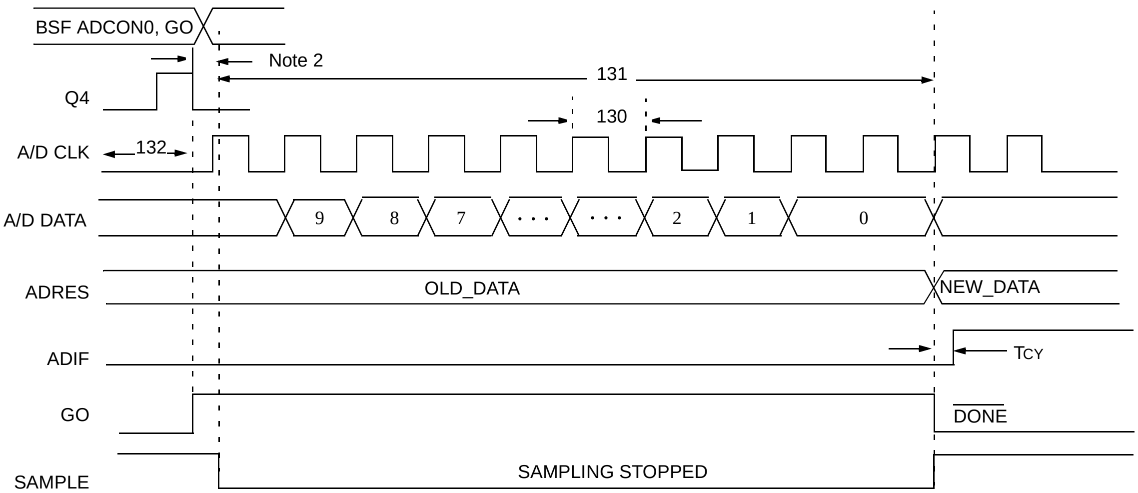
TABLE 21-6: CLKOUT AND I/O TIMING REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	**(1)**
11	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	**(1)**
12	TckR	CLKOUT rise time		—	35	100	ns	**(1)**
13	TckF	CLKOUT fall time		—	35	100	ns	**(1)**
14	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY + 20	ns	**(1)**
15	TioV2ckH	Port in valid before CLKOUT ↑		0.25TCY + 25	—	—	ns	**(1)**
16	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	**(1)**
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC18**C**XXX	100	—	—	ns	
18A			PIC18**LC**XXX	200	—	—	ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20	TioR	Port output rise time	PIC18**C**XXX	—	12	25	ns	
20A			PIC18**LC**XXX	—	—	50	ns	
21	TioF	Port output fall time	PIC18**C**XXX	—	12	25	ns	
21A			PIC18**LC**XXX	—	—	50	ns	
22††	TINP	INT pin high or low time		TCY	—	—	ns	
23††	TRBP	RB7:RB4 change INT high or low time		TCY	—	—	ns	
24††	TRCP	RC7:RC4 change INT high or low time		20			ns	

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 21-22: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

2: This is a minimal RC delay (typically 100 ns), which also disconnects the holding capacitor from the analog input.

TABLE 21-22: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
130	TAD	A/D clock period	PIC18**C**XXX	1.6	20(5)	μs	TOSC based, VREF ≥ 3.0V
			PIC18**LC**XXX	3.0	20(5)	μs	TOSC based, VREF full range
			PIC18**C**XXX	2.0	6.0	μs	A/D RC mode
			PIC18**LC**XXX	3.0	9.0	μs	A/D RC mode
131	TCNV	Conversion time (not including acquisition time) **(Note 1)**		11	12	TAD	
132	TACQ	Acquisition time **(Note 3)**		15 10	— —	μs μs	-40°C ≤ Temp ≤ 125°C 0°C ≤ Temp ≤ 125°C
135	TSWC	Switching Time from convert → sample		—	**(Note 4)**		
136	TAMP	Amplifier settling time **(Note 2)**		1	—	μs	This may be used if the “new” input voltage has not changed by more than 1 LSb (i.e., 5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 16.0 for minimum conditions, when input voltage has changed more than 1 LSb.

3: The time for the holding capacitor to acquire the “New” input voltage, when the voltage changes full scale after the conversion (AVDD to AVSS, or AVSS to AVDD). The source impedance (*RS*) on the input channels is 50 Ω.

4: On the next Q4 cycle of the device clock.

5: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

NOTES:

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